

Title (en)

METHOD FOR PRODUCING A BASE PLATE FOR AN ELECTRONIC MODULE

Title (de)

VERFAHREN ZUM HERSTELLEN EINER BODENPLATTE FÜR EIN ELEKTRONIKMODUL

Title (fr)

PROCÉDÉ DE FABRICATION D'UNE PLAQUE DE FOND POUR UN MODULE ÉLECTRONIQUE

Publication

EP 3710613 A1 20200923 (DE)

Application

EP 18789391 A 20181017

Priority

- DE 102017126590 A 20171113
- EP 2018078424 W 20181017

Abstract (en)

[origin: WO2019091734A1] The invention relates to a method for producing a base plate for an electronic module, wherein a plate made of a composite material, which contains a metallic component based on aluminum and a non-metallic component, is coated with a solderable layer. According to the invention, the carrier layer and the cover are deposited by means of PVD.

IPC 8 full level

C23C 14/02 (2006.01); **C23C 14/04** (2006.01); **C23C 14/18** (2006.01); **H05K 3/00** (2006.01)

CPC (source: EP IL KR US)

C23C 14/022 (2013.01 - EP IL KR US); **C23C 14/025** (2013.01 - EP IL KR US); **C23C 14/042** (2013.01 - EP IL KR US);
C23C 14/18 (2013.01 - EP IL KR US)

Citation (search report)

See references of WO 2019091734A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

WO 2019091734 A1 20190516; CA 3080428 A1 20190516; CN 111344430 A 20200626; CN 111344430 B 20220315;
DE 102017126590 A1 20190516; EP 3710613 A1 20200923; IL 274056 A 20200630; JP 2021502692 A 20210128; JP 7185689 B2 20221207;
KR 20200087131 A 20200720; US 2020270738 A1 20200827

DOCDB simple family (application)

EP 2018078424 W 20181017; CA 3080428 A 20181017; CN 201880073334 A 20181017; DE 102017126590 A 20171113;
EP 18789391 A 20181017; IL 27405620 A 20200419; JP 2020524047 A 20181017; KR 20207011813 A 20181017;
US 202015929581 A 20200511